REMARKS

Claims 1-14 are pending in this application. By this Amendment, Applicants amend claims 1, 4 and 7.

Claims 1-14 were rejected under 35 U.S.C. § 112, second paragraph, for allegedly being indefinite. Applicants have amended claim 1 to correct the alleged informality noted by the Examiner. Accordingly, Applicants respectfully request reconsideration and withdrawal of this rejection.

Claims 1-14 were rejected under 35 U.S.C. § 102(b) as being anticipated by Nakazawa et al. (U.S. 6,040,652). Applicants respectfully traverse this rejection.

Claim 1 has been amended to recite:

> "A method of manufacturing a laminated ceramic electronic component comprising the steps of:
> **preparing a first transfer sheet including a composite green sheet supported by a first supporting film, said composite green sheet including a conductor formed on a region of the first transfer sheet and at least one of a first ceramic area and a second ceramic area formed on another region of the first transfer sheet excluding the region of the first transfer sheet where the conductor is formed such that the conductor and the at least one of the first ceramic area and the ceramic second area do not overlap each other;**
> preparing a second transfer sheet including a ceramic green sheet supported by a second supporting film;
> a first transfer step of transferring the ceramic green sheet of at least one second transfer sheet on a lamination stage;
> a second transfer step of transferring the composite green sheet of at least one first transfer sheet on the at least one ceramic green sheet that was previously laminated;
> a third transfer step of transferring the ceramic green sheet of at least one second transfer sheet on the composite green sheet that was previously laminated; and
> firing a laminate obtained by the first, second and third transfer steps." (emphasis added)

With the unique combination and arrangement of features and method steps recited in Applicants' claim 1, including the step of "preparing a first transfer sheet including a composite green sheet supported by a first supporting film, said composite green sheet including a conductor formed on a region of the first transfer sheet and at least one of a first ceramic area and a second ceramic area formed on another region of

the first transfer sheet excluding the region of the first transfer sheet where the conductor is formed such that the conductor and the at least one of the first ceramic area and the second ceramic area do not overlap each other," Applicants have been able to provide a method of manufacturing a laminated ceramic electronic component in which the conductor is formed inside a sintered ceramic body, and the conductor and the inner structure of the sintered ceramic body are formed highly accurately and reliably via a greatly simplified process that significantly reduces the cost of the component (see, for example, the second full paragraph on page 3 of the originally filed specification).

The Examiner alleged that Nakazawa et al. teaches each and every feature and method step recited in Applicants' claim 1.

Claim 1 has been amended to recite the step of "preparing a first transfer sheet including a composite green sheet supported by a first supporting film, said composite green sheet including a conductor formed on a region of the first transfer sheet and at least one of a first ceramic area and a second ceramic area formed on another region of the first transfer sheet excluding the region of the first transfer sheet where the conductor is formed such that the conductor and the at least one of the first ceramic area and the second ceramic area do not overlap each other."

In contrast to Applicants' claim 1, Nakazawa et al. teaches that the conductor DP is formed **on top of a ceramic area GS** such that the conductor and the ceramic area GS **overlap each other** (see, for example, Figs. 7, 10 and 27 of Nakazawa et al.). In other words, at best, Nakazawa et al. teaches a step of preparing a first transfer sheet including a composite green sheet supported by a first supporting film BF, the composite green sheet including a conductor DP formed on a region of the first transfer sheet and **at least one of a first ceramic area and a second ceramic area GS formed on a region of the first transfer sheet including the region of the first transfer sheet where the conductor DP is formed** such that the conductor DP and the at least one of the first ceramic area and the second ceramic area GS **overlap each other**. Nakazawa et al. clearly fails to teach or suggest the step of "preparing a first transfer sheet including a composite green sheet supported by a first supporting film,

said composite green sheet including a conductor formed on a region of the first transfer sheet and **at least one of a first ceramic area and a second ceramic area formed on another region of the first transfer sheet excluding the region of the first transfer sheet where the conductor is formed** such that the conductor and the at least one of the first ceramic area and the second ceramic area **do not overlap each other**" (emphasis added) as recited in Applicants' claim 1. In fact, Nakazawa et al. clearly teaches the exact opposite process and arrangement of Applicants' claimed invention.

Accordingly, Applicants respectfully submit that Nakazawa et al. fails to teach or suggest the unique combination and arrangement of features and method steps recited in Applicants' claim 1.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claim 1 under 35 U.S.C. § 102(b) over Nakazawa et al.

In view of the foregoing amendments and remarks, Applicants respectfully submit that Claim 1 is allowable. Claims 2-14 depend upon claim 1, and are therefore allowable for at least the reasons that claim 1 is allowable.

In view of the foregoing amendments and remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

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